**PCN: V11-222-475316-0A**

# Product Change Notice

## THIS CHANGE AFFECTS HERMETIC OPTOCOUPLERS ONLY

**Issue Date: 11 February 2011**
**HOC222**
**CAGE Code 50434**

## Change Type:

Die wafer process change.

## Parts Affected:

See following page for full part number list.

## Description and Extent of Change:

After the successful completion of die qualification, Avago Technologies will begin to use IC's fabricated utilizing a process change from a solid planar source predeposition doping to a liquid source predeposition doping. This changes the method of depositing phosphorus onto the wafers.

This change affects Class H only. Class K products are not affected at this time. There are no data sheet parameters affected by this change.

## Reasons for Change:

Enhanced process uniformity and stability.

## Effective Date of Change:

This change will be in effect upon current die depletion. Controls are in place to assure traceability of the IC to the appropriate supplier for all products affected.
GIDEP Product Change Notice, Document JL8-C-11-0001, reflecting this change was published and posted in February 2011. Please contact Debbi Beauchesne at 408-435-4143 or debbi.beauchesne@avagotech.com if there are any questions or concerns.

*Shelley A. Sinclair*
Product Line Manager

*Ah Chee Neo*
Quality Assurance Manager

## Parts Affected:

### Avago Part Number Class H:

4N55/883B
4N55/883B#100
4N55/883B#200
4N55/883B#300
HCPL-5501
HCPL-5501#100
HCPL-5501#200
HCPL-5501#300
HCPL-5531
HCPL-5531#100
HCPL-5531#200
HCPL-5531#300
HCPL-6531
HCPL-6551

### DSCC SMD:

5962-8767901EC
5962-8767901UC
5962-8767901EA
5962-8767901TA
5962-8767901UA
5962-9085401HPC
5962-9085401HYC
5962-9085401HPA
5962-9085401HXA
5962-9085401HYA
5962-8767902PC
5962-8767902YC
5962-8767902PA
5962-8767902XA
5962-8767902YA
5962-87679032A
5962-8767904FC